

CLAIMS

What is claimed is:

- 5 1. A leadframe packaging apparatus comprising:
 - a die;
 - at least two separated die pads each connected to a corresponding voltage
 - level thereof;
 - a plurality of leadfingers; and
 - 10 at least one passive component having two ends each connected to one of
 - said two separated die pads.
2. The leadframe packaging apparatus of claim 1 wherein said voltage level is a
- power source voltage level and a ground voltage level.
- 15 3. The leadframe packaging apparatus of claim 2 wherein said power source
- voltage level and said ground voltage level is supplied by a printed circuit board,
- which is further fixedly connected with said leadframe packaging apparatus.
- 20 4. The leadframe packaging apparatus of claim 1 further comprising a busbar
- disposed between two non-adjacent leadfingers.
5. A leadframe packaging apparatus comprising:
 - a die;
 - 25 a diepad;
 - a plurality of leadfingers; and

at least one passive component having two ends respectively connected to two leadfingers having two different voltage levels.

6. The leadframe packaging apparatus of claim 5 wherein the voltage levels
5 comprises a power source voltage level and a ground voltage level.
7. The leadframe packaging apparatus of claim 6 wherein said power source voltage and said ground voltage level are supplied by a printed circuit board.
- 10 8. A packaging method for a leadframe packaging apparatus comprising steps as follows:
 - preparing an integrated circuit die;
 - adhering said integrated circuit die into a die pad;
 - preparing at least one passive component;
 - 15 wirebonding said integrated circuit die;
 - preparing a molding compound for placing said integrated circuit die, said die pad, and said passive component therein;
 - defining said leadfingers outside of said molding compound as first leadfinger sections and said leadfingers inside of said molding compound as
20 second leadfinger sections; and
 - electrically connecting said first leadfinger sections with a printed circuit board and said second leadfinger sections with said integrated circuit board.
9. The packaging method of claim 8 further comprising a step of having a busbar
25 bridged two non-adjacent said second leadfinger sections.

10. The packaging method of claim 9, wherein said passive component further
bridges one of two non-adjacent said second leadfinger sections and said busbar.
11. The packaging method of claim 8 wherein the passive component is further
5 bridged between two adjacent said second leadfinger sections.
12. The packaging method of claim 8 further comprising a step of metalizing a
bottom surface of said integrated circuit die before adhering said integrated
circuit die into said die pad.
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13. The packaging method of claim 8 wherein wirebonding said integrated circuit die
is to wirebond a plurality of metal wires to said second leadfinger sections.
14. The packaging method of claim 8 wherein said leadfingers is made of an alloy.
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15. The packaging method of claim 8 wherein said passive component further
bridges two adjacent said first leadfinger sections.